



<i>flow PIM 1</i>	1200 V / 25 A
<div style="border: 1px solid black; padding: 5px; margin-bottom: 10px;"> <p style="text-align: center; background-color: #ccc; margin: 0;">Features</p> <ul style="list-style-type: none"> 3phase rectifier, optional BRC, Inverter, NTC Very compact housing, easy to route Trench Fieldstop IGBT's for low saturation losses </div> <div style="border: 1px solid black; padding: 5px; margin-bottom: 10px;"> <p style="text-align: center; background-color: #ccc; margin: 0;">Target Applications</p> <ul style="list-style-type: none"> Industrial drives Embedded drives </div> <div style="border: 1px solid black; padding: 5px;"> <p style="text-align: center; background-color: #ccc; margin: 0;">Types</p> <ul style="list-style-type: none"> V23990-P589-A-PM V23990-P589-C-PM </div>	<div style="border: 1px solid black; padding: 5px; margin-bottom: 10px;"> <p style="text-align: center; background-color: #ccc; margin: 0;"><i>flow 1 17mm housing</i></p> </div> <div style="border: 1px solid black; padding: 5px;"> <p style="text-align: center; background-color: #ccc; margin: 0;">Schematic</p> </div>

Maximum Ratings

$T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Rectifier Diode				
Repetitive peak reverse voltage	V_{RRM}		1600	V
DC forward current	I_{FAV}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	45	A
Surge (non-repetitive) forward current	I_{FSM}	$t_p = 10\text{ ms}$	280	A
I2t-value	I^2t		390	A ² s
Power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	59	W
Maximum Junction Temperature	T_{jmax}		150	°C
Inverter Switch				
Collector-emitter breakdown voltage	V_{CE}		1200	V
DC collector current	I_C	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	31	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	75	A
Power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	74	W
Gate-emitter peak voltage	V_{GE}		±20	V
Maximum Junction Temperature	T_{jmax}		150	°C
Inverter Diode				
Peak Repetitive Reverse Voltage	V_{RRM}		1200	V
DC forward current	I_F	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	33	A
Power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	58	W
Maximum Junction Temperature	T_{jmax}		150	°C

**Maximum Ratings** $T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
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Brake Switch

Collector-emitter breakdown voltage	V_{CE}		1200	V
DC collector current	I_C	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	21	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	45	A
Power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	59	W
Gate-emitter peak voltage	V_{GE}		±20	V
Maximum Junction Temperature	T_{jmax}		150	°C

Brake Diode

Peak Repetitive Reverse Voltage	V_{RRM}		1200	V
DC forward current	I_F	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	8	A
Power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	32	W
Maximum Junction Temperature	T_{jmax}		150	°C

Thermal Properties

Storage temperature	T_{stg}		-40...+125	°C
Operation temperature under switching condition	T_{op}		-40...+($T_{jmax} - 25$)	°C

Isolation Properties

Isolation voltage	V_{is}	$t = 2\text{ s}$ DC Test Voltage	4000	V
Creepage distance			min 12,7	mm
Clearance			min 12,7	mm
Comparative tracking index	CTI		>200	



Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
		V_{GE} [V] V_{GS} [V]	V_r [V] V_{CE} [V] V_{DS} [V]	I_C [A] I_F [A] I_D [A]	T_j [°C]	Min	Typ	Max		

Rectifier Diode

Forward voltage	V_F				30	25 125		1,17 1,12	1,3		v
Threshold voltage (for power loss calc. only)	V_{to}					25 125		0,9 0,77			v
Slope resistance (for power loss calc. only)	r_t					25 125		9 11			mΩ
Reverse current	I_r			1600		25				20	mA
Thermal resistance junction to sink	$R_{th(j-s)}$	phase-change material $\lambda = 3,4$ W/mK						1,19			K/W

Inverter Switch

Gate emitter threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}$				0,001	25	5	5,8	6,5	v	
Collector-emitter saturation voltage	V_{CESat}		15			25 125	25 125	1,35	1,79 2,05	2,05	v	
Collector-emitter cut-off current incl. Diode	I_{CES}		0	1200			25			150	μA	
Gate-emitter leakage current	I_{GES}		20	0			25			600	nA	
Integrated Gate resistor	R_{gint}								8		Ω	
Turn-on delay time	$t_{d(on)}$	$R_{goff} = 36$ Ω $R_{gon} = 36$ Ω	±15	600	25	25 125	25 125		266 76		ns	
Rise time	t_r											18 26
Turn-off delay time	$t_{d(off)}$											400 487
Fall time	t_f											107 179
Turn-on energy loss	E_{on}											2,18 3,45
Turn-off energy loss	E_{off}											1,82 2,57
Input capacitance	C_{ies}								1808			
Output capacitance	C_{oss}	$f = 1$ MHz	0	25		25			95		pF	
Reverse transfer capacitance	C_{rss}								82			
Gate charge	Q_G		15	960	25	25			155		nC	
Thermal resistance junction to sink	$R_{th(j-s)}$	phase-change material $\lambda = 3,4$ W/mK							0,94		K/W	

Inverter Diode

Diode forward voltage	V_F					30	25 125		2,17 1,74		v
Peak reverse recovery current	I_{RRM}						25 125		39,08 46,1		A
Reverse recovery time	t_{rr}						25 125		43 332		ns
Reverse recovered charge	Q_{rr}	$R_{goff} = 36$ Ω	±15	600	25	25 125	25 125		2,04 4,82		μC
Peak rate of fall of recovery current	$(di_{rr}/dt)_{max}$					25 125	25 125		3582 1622		A/μs
Reverse recovered energy	E_{rec}					25 125	25 125		0,6 1,42		mWs
Thermal resistance junction to sink	$R_{th(j-s)}$	phase-change material $\lambda = 3,4$ W/mK							1,20		K/W



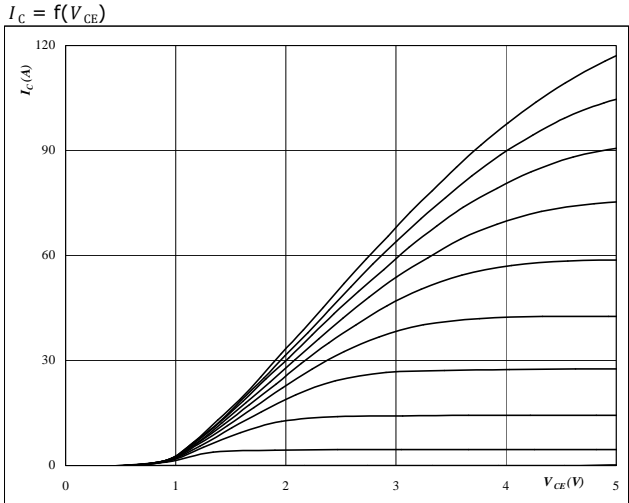
Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
		V_{GE} [V] V_{GS} [V]	V_r [V] V_{CE} [V] V_{DS} [V]	I_C [A] I_F [A] I_D [A]	T_j [°C]	Min	Typ	Max		
Brake Switch										
Gate emitter threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}$			0,0006	25	5	5,8	6,5	V
Collector-emitter saturation voltage	V_{CEsat}		15		15	25 125	1,35	1,77 2,01	2,05	V
Collector-emitter cut-off incl diode	I_{CES}		0	1200		25			2	µA
Gate-emitter leakage current	I_{GES}		20	0		25			120	nA
Integrated Gate resistor	R_{gint}							none		Ω
Turn-on delay time	$t_{d(on)}$	$R_{goff} = 20 \Omega$ $R_{gon} = 40 \Omega$	15	600	15	25		36		ns
Rise time	t_r					125		36		
Turn-off delay time	$t_{d(off)}$					25		21		
Fall time	t_f					125		25		
Turn-on energy loss	E_{on}					25		312		
Turn-off energy loss	E_{off}					125		375		
Input capacitance	C_{ies}	$f = 1 \text{ MHz}$	0	25	25			1090		pF
Output capacitance	C_{oss}							58		
Reverse transfer capacitance	C_{rss}							48		
Gate charge	Q_G		15	960	15	25		85		nC
Thermal resistance junction to sink	$R_{th(j-s)}$	phase-change material $\lambda = 3,4 \text{ W/mK}$						1,19		K/W
Brake Diode										
Diode forward voltage	V_F				6	25 125		2,1 1,56		V
Reverse leakage current	I_r			1200		25			50	µA
Peak reverse recovery current	I_{RRM}	$R_{goff} = 40 \Omega$	15	600	15	25		14,19		A
Reverse recovery time	t_{rr}					125		19,42		
Reverse recovered charge	Q_{rr}					25		254		
Peak rate of fall of recovery current	$(di_{rr}/dt)_{max}$					125		385		
Reverse recovery energy	E_{rec}					25		1,1		
						125		1,1		
Thermal resistance junction to sink	$R_{th(j-s)}$	phase-change material $\lambda = 3,4 \text{ W/mK}$						2,1		K/W
Thermistor										
Rated resistance	R					25		21500		Ω
Deviation of R_{100}	$\Delta_{R/R}$	$R_{100} = 1486 \Omega$				100	-4,5		4,5	%
Power dissipation	P					25		210		mW
Power dissipation constant						25		3,5		mW/K
B-value	$B_{(25/50)}$	Tol. ±3%				25		3884		K
B-value	$B_{(25/100)}$	Tol. ±3%				25		3964		K
Vincotech NTC Reference									F	



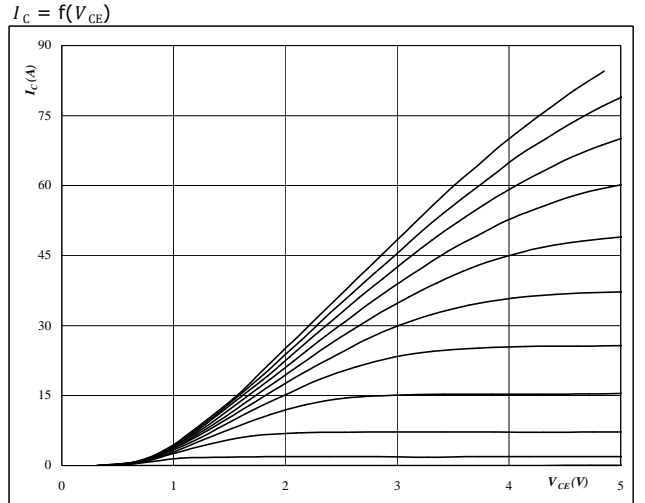
Inverter Characteristics

figure 1. IGBT
Typical output characteristics



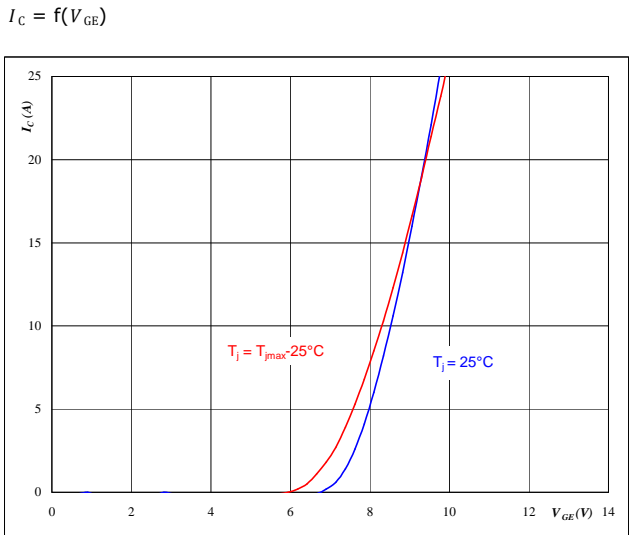
At
 $t_p = 250 \mu s$
 $T_j = 25 \text{ }^\circ C$
 V_{GE} from 6 V to 16 V in steps of 1 V

figure 2. IGBT
Typical output characteristics



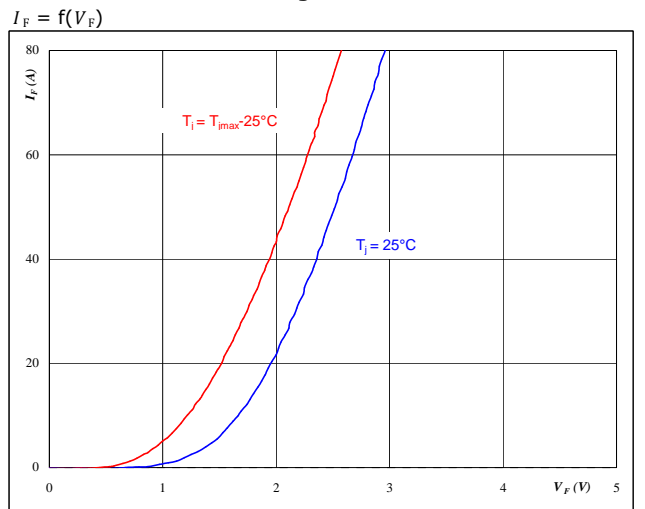
At
 $t_p = 250 \mu s$
 $T_j = 125 \text{ }^\circ C$
 V_{GE} from 6 V to 16 V in steps of 1 V

figure 3. IGBT
Typical transfer characteristics



At
 $t_p = 250 \mu s$
 $V_{CE} = 10 V$

figure 4. FWD
Typical diode forward current as a function of forward voltage



At
 $t_p = 250 \mu s$

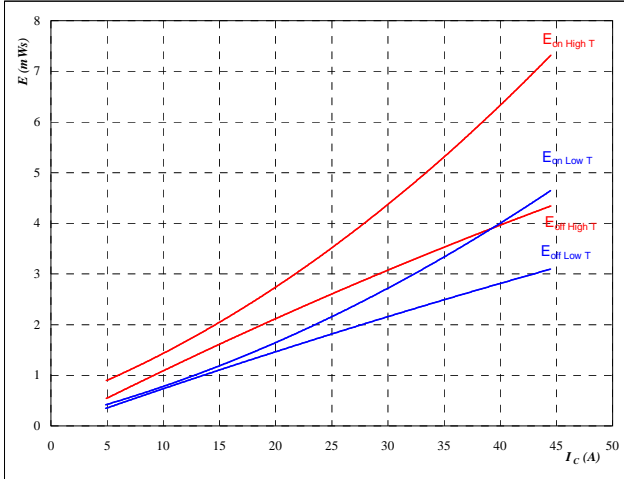


Inverter Characteristics

figure 5. IGBT

Typical switching energy losses as a function of collector current

$E = f(I_C)$

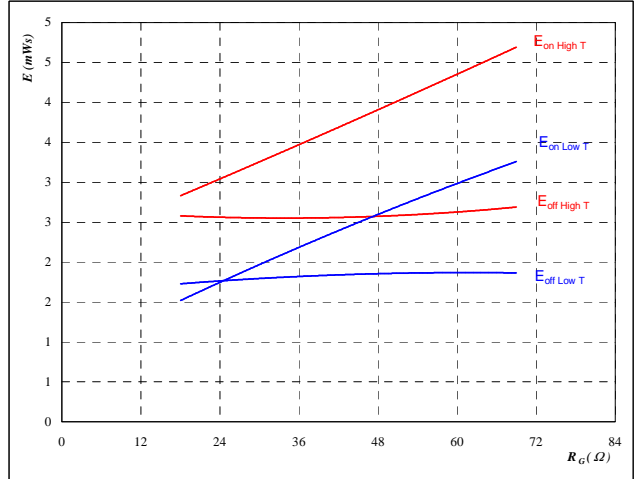


With an inductive load at
 $T_j = 25/125 \text{ } ^\circ\text{C}$
 $V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $R_{gon} = 36 \text{ } \Omega$
 $R_{goff} = 36 \text{ } \Omega$

figure 6. IGBT

Typical switching energy losses as a function of gate resistor

$E = f(R_G)$

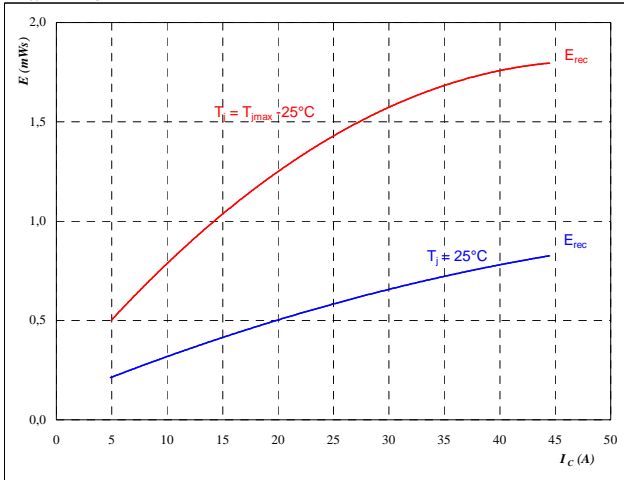


With an inductive load at
 $T_j = 25/125 \text{ } ^\circ\text{C}$
 $V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $I_C = 25 \text{ A}$

figure 7. FWD

Typical reverse recovery energy loss as a function of collector current

$E_{rec} = f(I_C)$

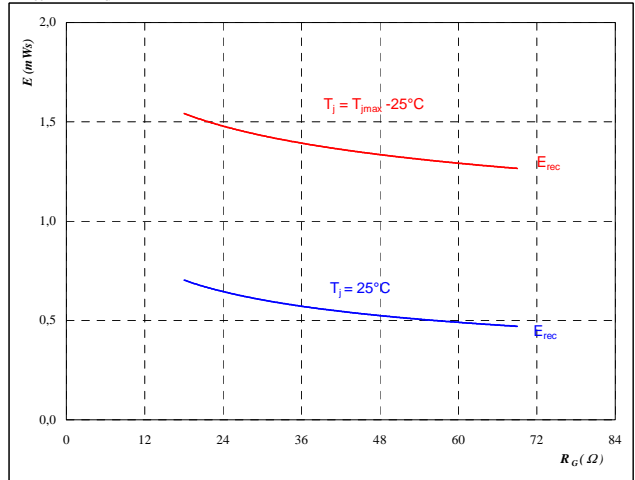


With an inductive load at
 $T_j = 25/125 \text{ } ^\circ\text{C}$
 $V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $R_{gon} = 36 \text{ } \Omega$

figure 8. FWD

Typical reverse recovery energy loss as a function of gate resistor

$E_{rec} = f(R_G)$



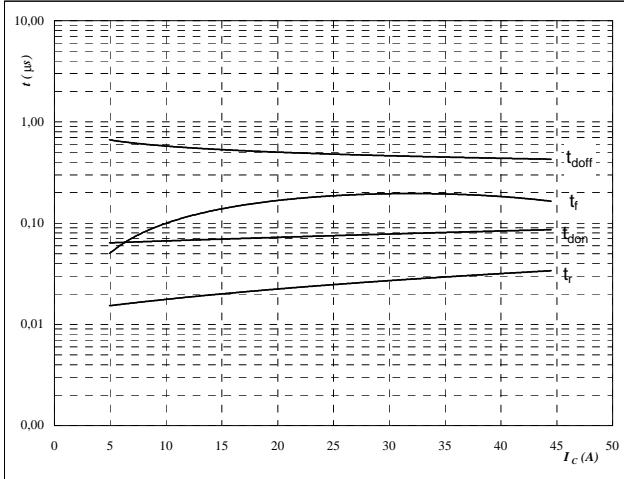
With an inductive load at
 $T_j = 25/125 \text{ } ^\circ\text{C}$
 $V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $I_C = 25 \text{ A}$



Inverter Characteristics

figure 9. IGBT

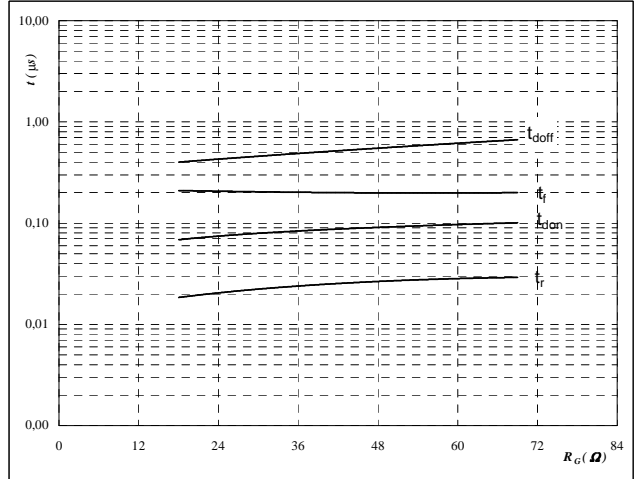
Typical switching times as a function of collector current
 $t = f(I_C)$



With an inductive load at
 $T_j = 125 \text{ } ^\circ\text{C}$
 $V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $R_{gon} = 36 \text{ } \Omega$
 $R_{goff} = 36 \text{ } \Omega$

figure 10. IGBT

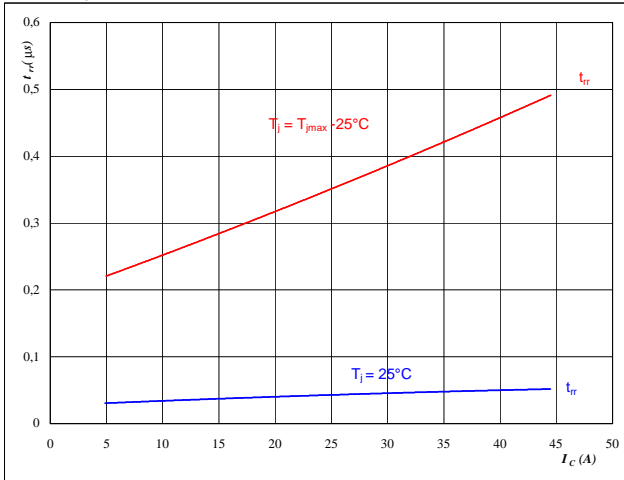
Typical switching times as a function of gate resistor
 $t = f(R_G)$



With an inductive load at
 $T_j = 125 \text{ } ^\circ\text{C}$
 $V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $I_C = 25 \text{ A}$

figure 11. FWD

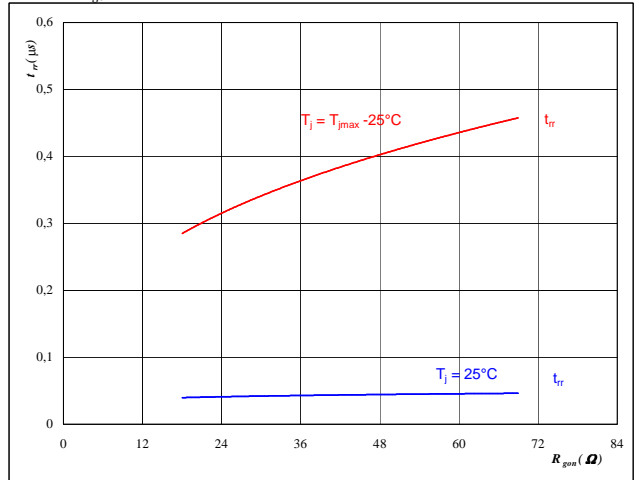
Typical reverse recovery time as a function of collector current
 $t_{rr} = f(I_C)$



At
 $T_j = 25/125 \text{ } ^\circ\text{C}$
 $V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $R_{gon} = 36 \text{ } \Omega$

figure 12. FWD

Typical reverse recovery time as a function of IGBT turn on gate resistor
 $t_{rr} = f(R_{gon})$



At
 $T_j = 25/125 \text{ } ^\circ\text{C}$
 $V_R = 600 \text{ V}$
 $I_F = 25 \text{ A}$
 $V_{GE} = \pm 15 \text{ V}$

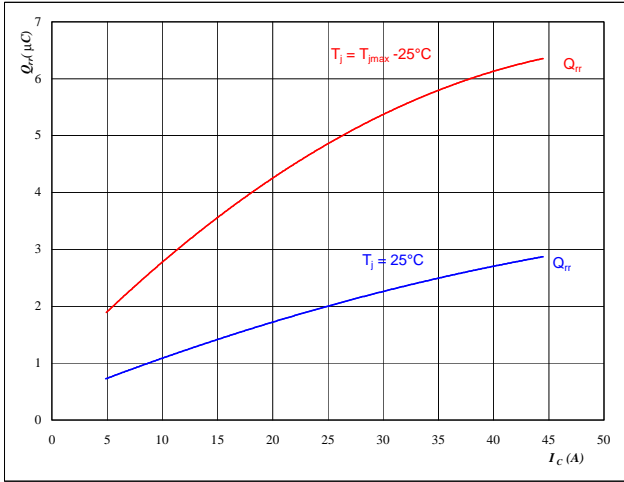


Inverter Characteristics

figure 13. FWD

Typical reverse recovery charge as a function of collector current

$Q_{rr} = f(I_C)$

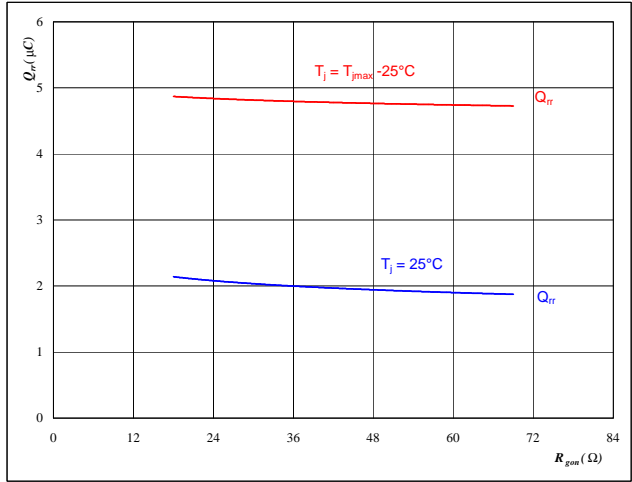


At
 $T_j = 25/125 \text{ } ^\circ\text{C}$
 $V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $R_{gon} = 36 \text{ } \Omega$

figure 14. FWD

Typical reverse recovery charge as a function of IGBT turn on gate resistor

$Q_{rr} = f(R_{gon})$

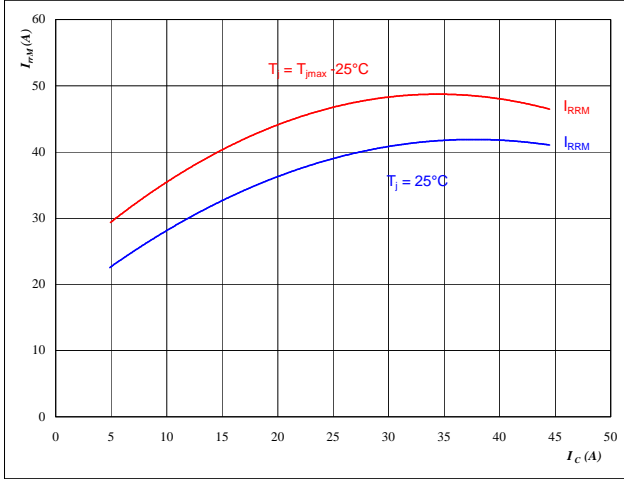


At
 $T_j = 25/125 \text{ } ^\circ\text{C}$
 $V_R = 600 \text{ V}$
 $I_F = 25 \text{ A}$
 $V_{GE} = \pm 15 \text{ V}$

figure 15. FWD

Typical reverse recovery current as a function of collector current

$I_{RRM} = f(I_C)$

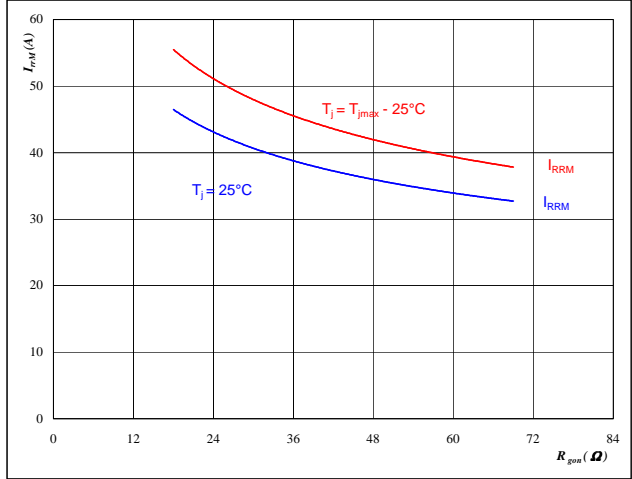


At
 $T_j = 25/125 \text{ } ^\circ\text{C}$
 $V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $R_{gon} = 36 \text{ } \Omega$

figure 16. FWD

Typical reverse recovery current as a function of IGBT turn on gate resistor

$I_{RRM} = f(R_{gon})$



At
 $T_j = 25/125 \text{ } ^\circ\text{C}$
 $V_R = 600 \text{ V}$
 $I_F = 25 \text{ A}$
 $V_{GE} = \pm 15 \text{ V}$

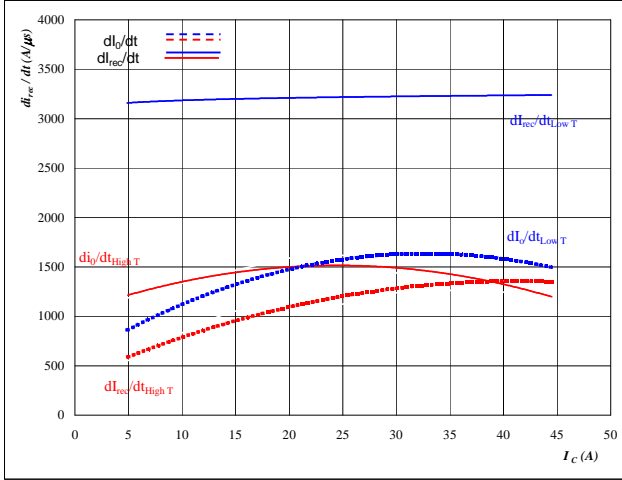


Inverter Characteristics

figure 17. FWD

Typical rate of fall of forward and reverse recovery current as a function of collector current

$$dI_0/dt, dI_{rec}/dt = f(I_C)$$

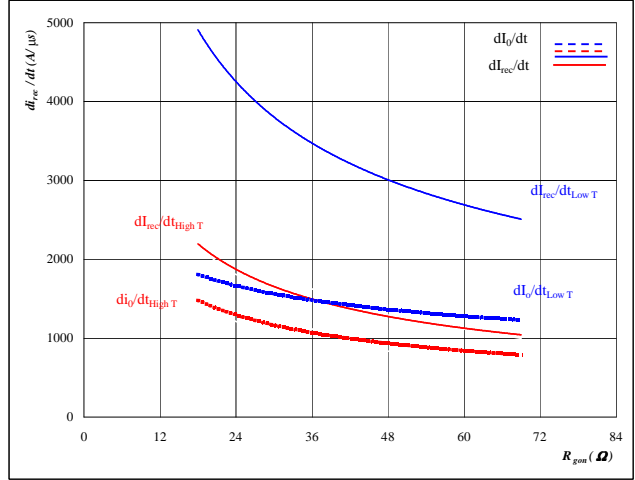


At
 $T_j = 25/125 \text{ } ^\circ\text{C}$
 $V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $R_{gon} = 36 \text{ } \Omega$

figure 18. FWD

Typical rate of fall of forward and reverse recovery current as a function of IGBT turn on gate resistor

$$dI_0/dt, dI_{rec}/dt = f(R_{gon})$$

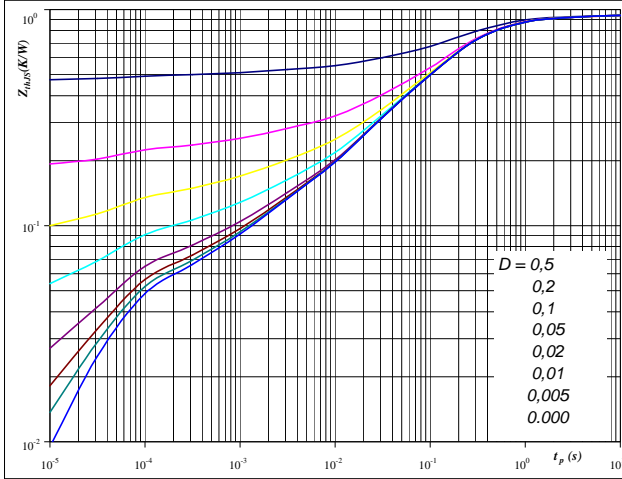


At
 $T_j = 25/125 \text{ } ^\circ\text{C}$
 $V_R = 600 \text{ V}$
 $I_F = 25 \text{ A}$
 $V_{GE} = \pm 15 \text{ V}$

figure 19. IGBT

IGBT transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



At
 $D = t_p / T$
 $R_{th(j-s)} = 0,94 \text{ K/W}$

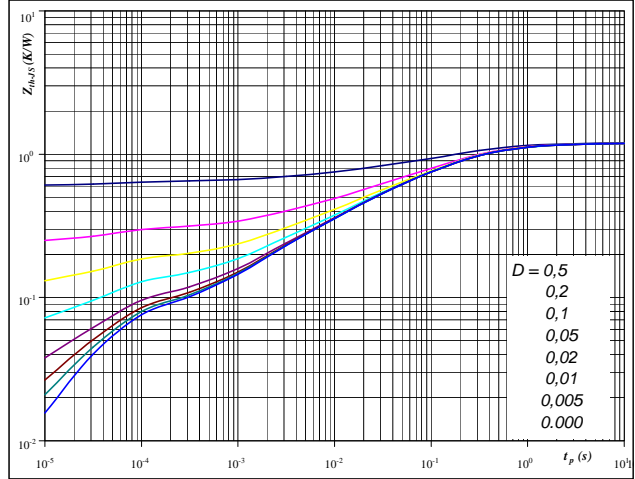
IGBT thermal model values

R (K/W)	Tau (s)
5,25E-02	3,57E+00
3,04E-01	4,16E-01
3,64E-01	1,16E-01
1,22E-01	1,52E-02
5,10E-02	1,15E-03
5,03E-02	5,13E-05

figure 20. FWD

FWD transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



At
 $D = t_p / T$
 $R_{th(j-s)} = 1,20 \text{ K/W}$

FWD thermal model values

R (K/W)	Tau (s)
2,86E-02	1,01E+02
8,35E-02	1,99E+00
3,35E-01	3,21E-01
3,59E-01	8,30E-02
2,23E-01	1,29E-02
1,07E-01	1,77E-03
7,67E-02	4,66E-05

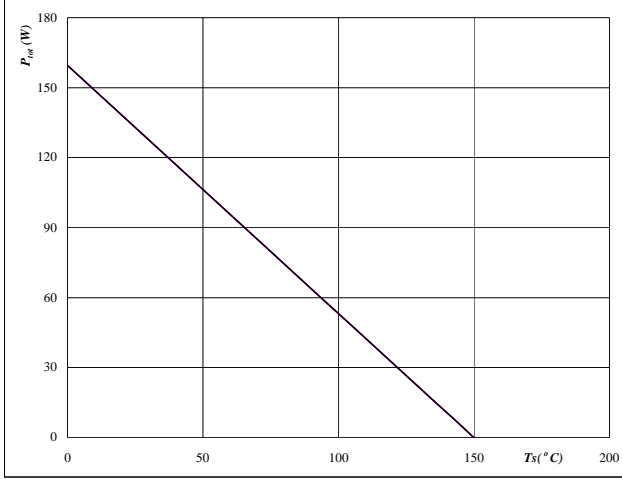


Inverter Characteristics

figure 21. IGBT

Power dissipation as a function of heatsink temperature

$$P_{tot} = f(T_s)$$

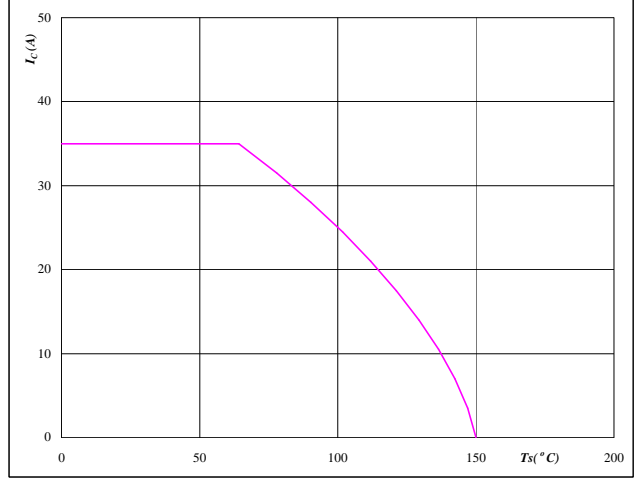


At
 $T_j = 150 \text{ °C}$

figure 22. IGBT

Collector current as a function of heatsink temperature

$$I_C = f(T_s)$$

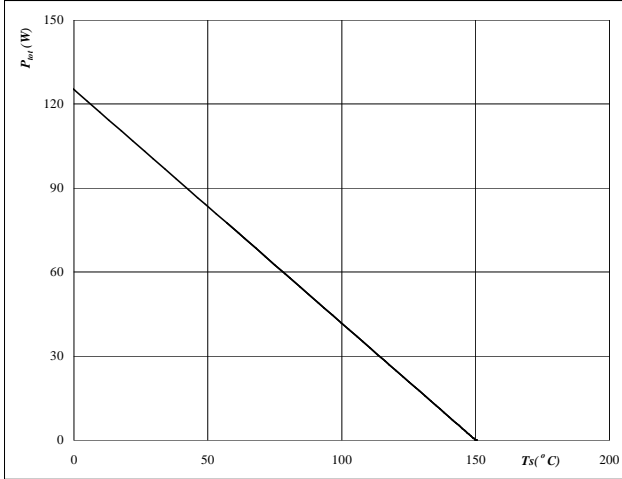


At
 $T_j = 150 \text{ °C}$
 $V_{GE} = 15 \text{ V}$

figure 23. FWD

Power dissipation as a function of heatsink temperature

$$P_{tot} = f(T_s)$$

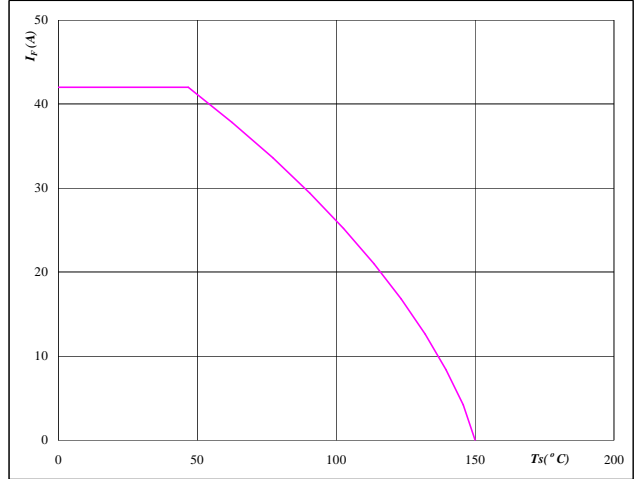


At
 $T_j = 150 \text{ °C}$

figure 24. FWD

Forward current as a function of heatsink temperature

$$I_F = f(T_s)$$



At
 $T_j = 150 \text{ °C}$

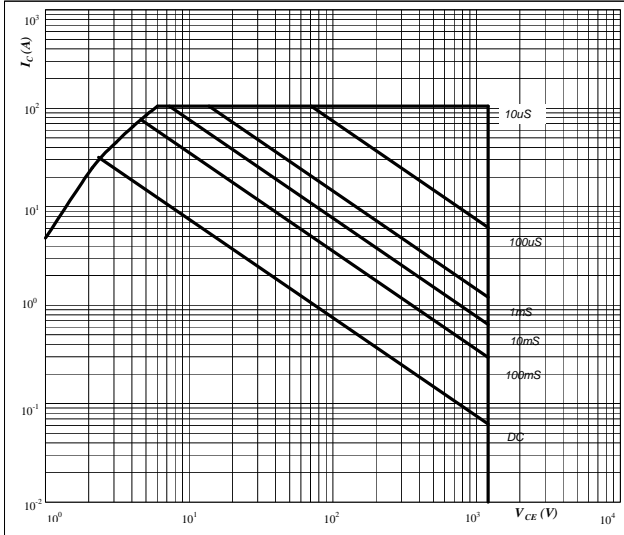


Inverter Characteristics

figure 25. IGBT

Safe operating area as a function of collector-emitter voltage

$I_C = f(V_{CE})$

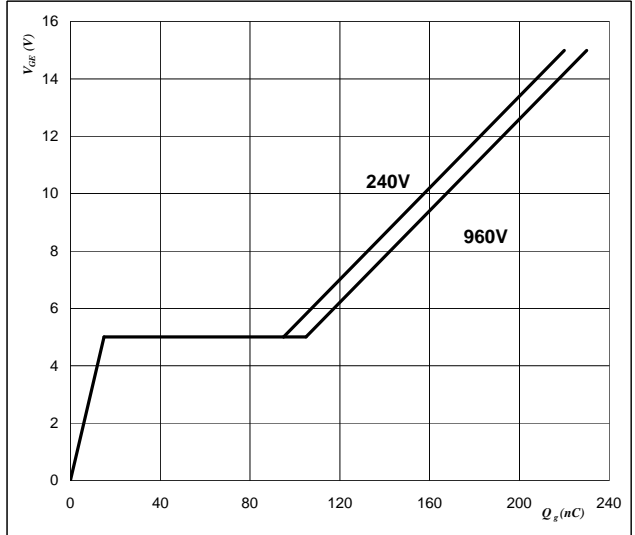


At
 $D =$ single pulse
 $T_s =$ 80 °C
 $V_{GE} =$ ±15 V
 $T_j = T_{jmax}$ °C

figure 26. IGBT

Gate voltage vs Gate charge

$V_{GE} = f(Q_g)$

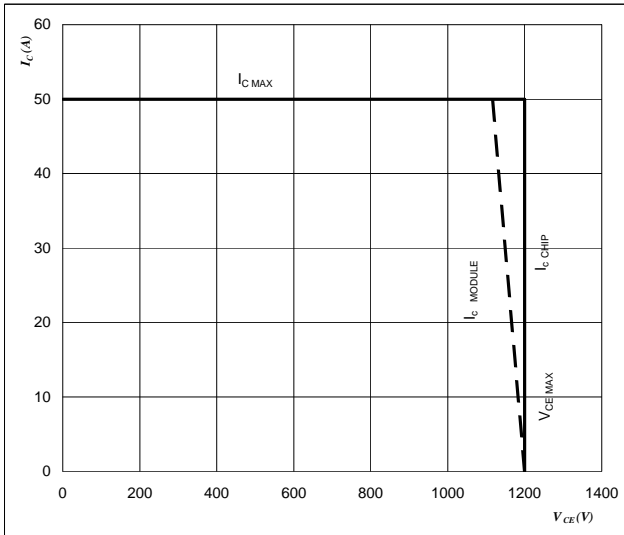


At
 $I_C =$ 25 A

figure 29. IGBT

Reverse bias safe operating area

$I_C = f(V_{CE})$



At
 $T_j =$ 124 °C
 $R_{gon} =$ 36 Ω
 $R_{goff} =$ 36 Ω

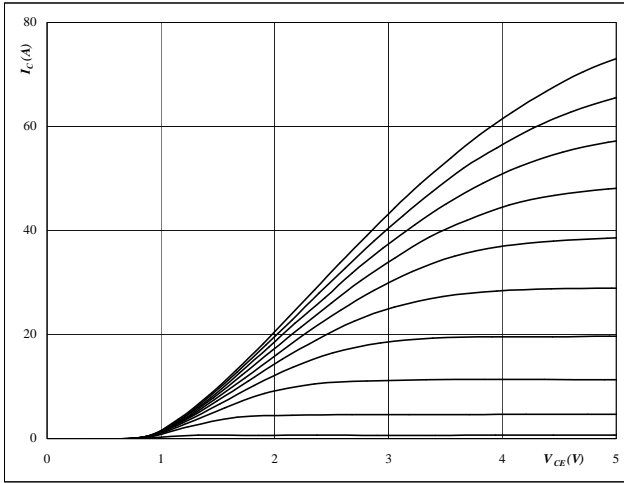


Brake Characteristics

figure 1. IGBT

Typical output characteristics

$I_C = f(V_{CE})$

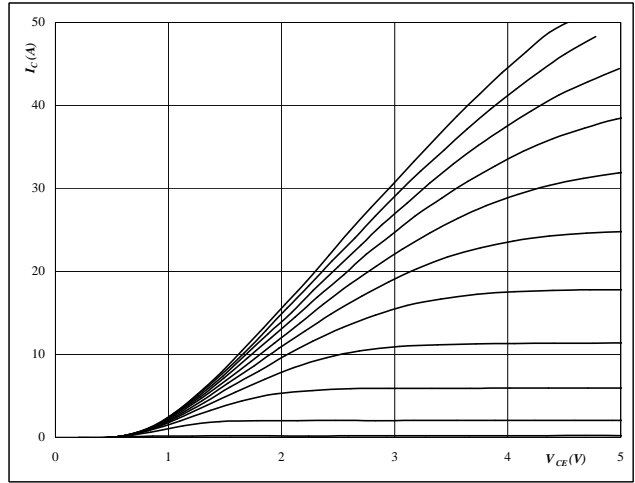


At
 $t_p = 250 \mu s$
 $T_j = 25 \text{ }^\circ C$
 V_{GE} from 6 V to 16 V in steps of 1 V

figure 2. IGBT

Typical output characteristics

$I_C = f(V_{CE})$

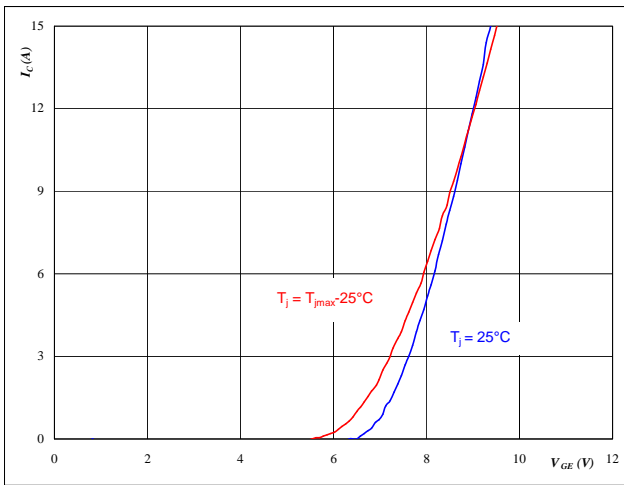


At
 $t_p = 250 \mu s$
 $T_j = 125 \text{ }^\circ C$
 V_{GE} from 6 V to 16 V in steps of 1 V

figure 3. IGBT

Typical transfer characteristics

$I_C = f(V_{GE})$

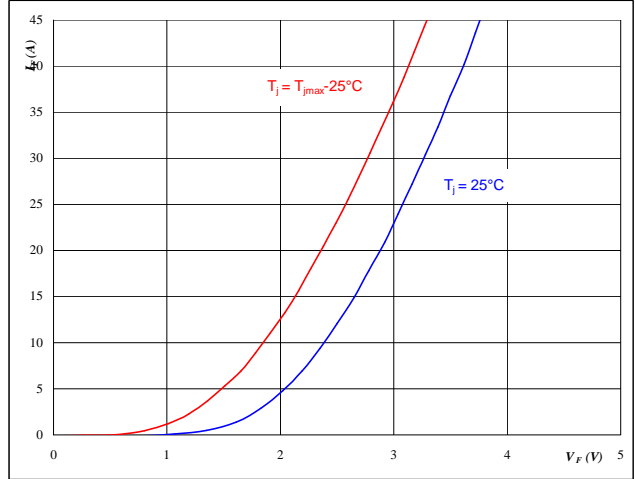


At
 $t_p = 250 \mu s$
 $V_{CE} = 10 V$

figure 4. FWD

Typical diode forward current as a function of forward voltage

$I_F = f(V_F)$



At
 $t_p = 250 \mu s$

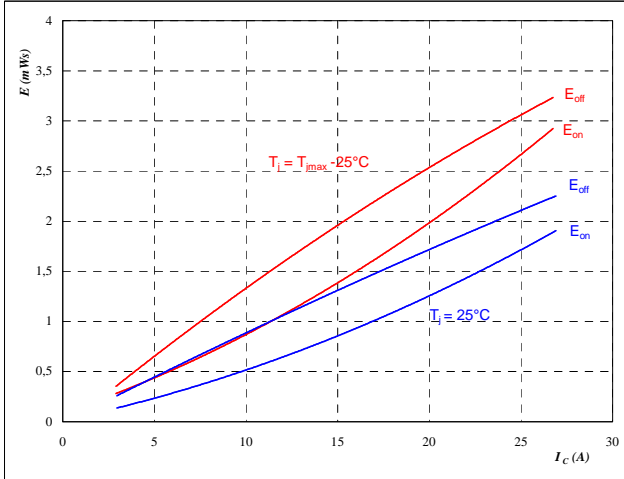


Brake Characteristics

figure 5. IGBT

Typical switching energy losses as a function of collector current

$E = f(I_C)$

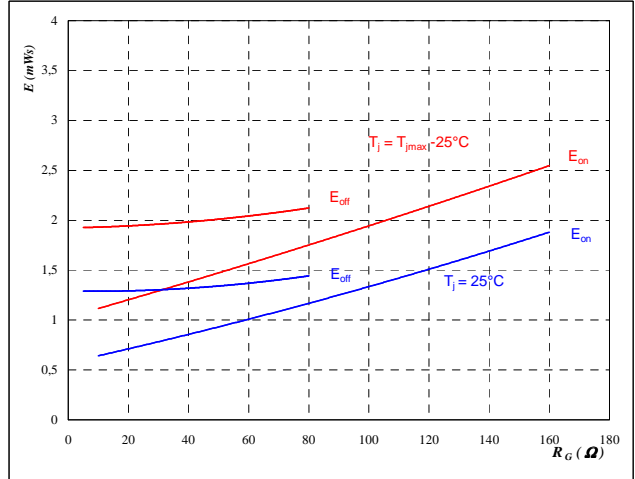


With an inductive load at
 $T_j = 25/125 \text{ } ^\circ\text{C}$
 $V_{CE} = 600 \text{ V}$
 $V_{GE} = 15 \text{ V}$
 $R_{gon} = 40 \text{ } \Omega$
 $R_{goff} = 20 \text{ } \Omega$

figure 6. IGBT

Typical switching energy losses as a function of gate resistor

$E = f(R_G)$

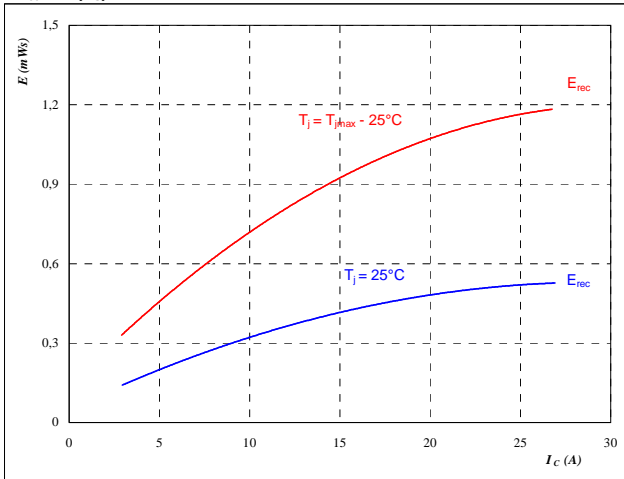


With an inductive load at
 $T_j = 25/125 \text{ } ^\circ\text{C}$
 $V_{CE} = 600 \text{ V}$
 $V_{GE} = 15 \text{ V}$
 $I_C = 15 \text{ A}$

figure 7. FWD

Typical reverse recovery energy loss as a function of collector current

$E_{rec} = f(I_C)$

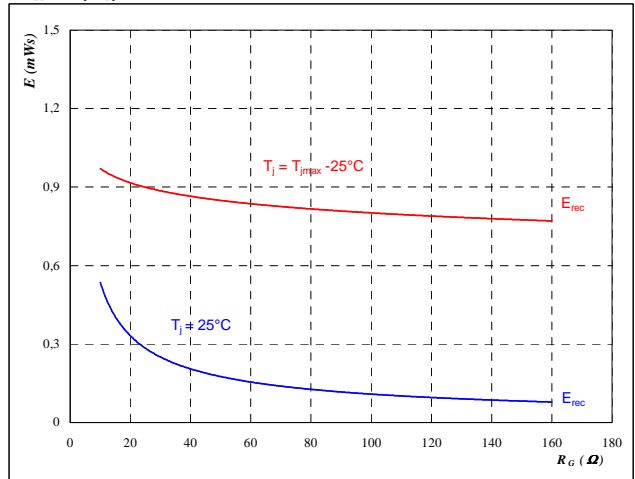


With an inductive load at
 $T_j = 25/125 \text{ } ^\circ\text{C}$
 $V_{CE} = 600 \text{ V}$
 $V_{GE} = 15 \text{ V}$
 $R_{gon} = 40 \text{ } \Omega$

figure 8. FWD

Typical reverse recovery energy loss as a function of gate resistor

$E_{rec} = f(R_G)$



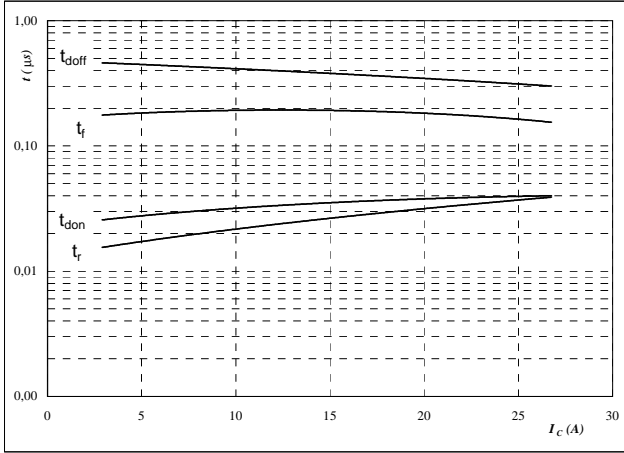
With an inductive load at
 $T_j = 25/125 \text{ } ^\circ\text{C}$
 $V_{CE} = 600 \text{ V}$
 $V_{GE} = 15 \text{ V}$
 $I_C = 15 \text{ A}$



Brake Characteristics

figure 9. IGBT

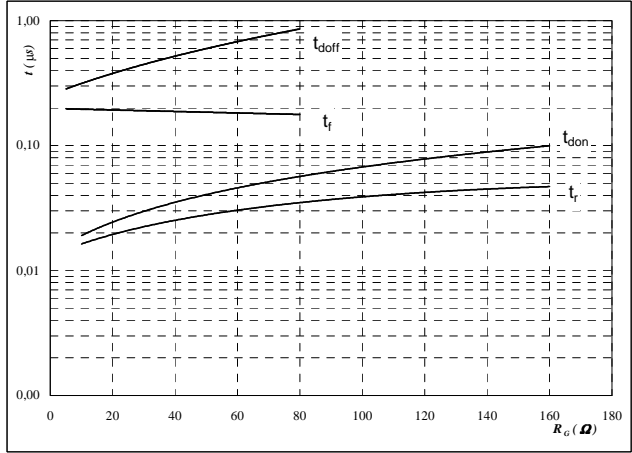
Typical switching times as a function of collector current
 $t = f(I_C)$



With an inductive load at
 $T_j = 125 \text{ } ^\circ\text{C}$
 $V_{CE} = 600 \text{ V}$
 $V_{GE} = 15 \text{ V}$
 $R_{gon} = 40 \text{ } \Omega$
 $R_{goff} = 20 \text{ } \Omega$

figure 10. IGBT

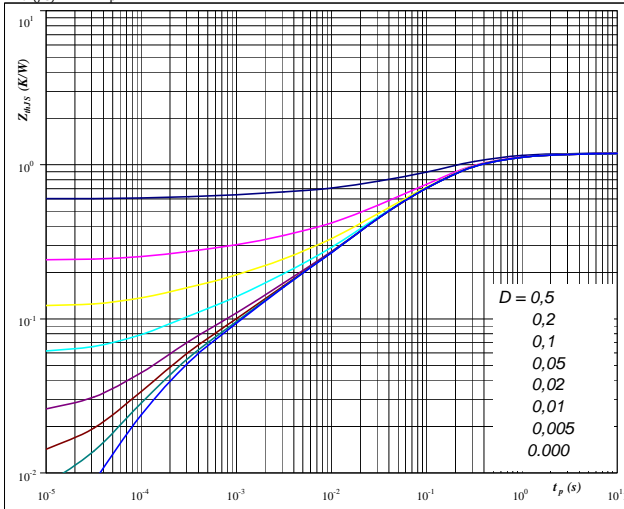
Typical switching times as a function of gate resistor
 $t = f(R_G)$



With an inductive load at
 $T_j = 125 \text{ } ^\circ\text{C}$
 $V_{CE} = 600 \text{ V}$
 $V_{GE} = 15 \text{ V}$
 $I_C = 15 \text{ A}$

figure 11. IGBT

IGBT transient thermal impedance as a function of pulse width
 $Z_{th(f-s)} = f(t_p)$

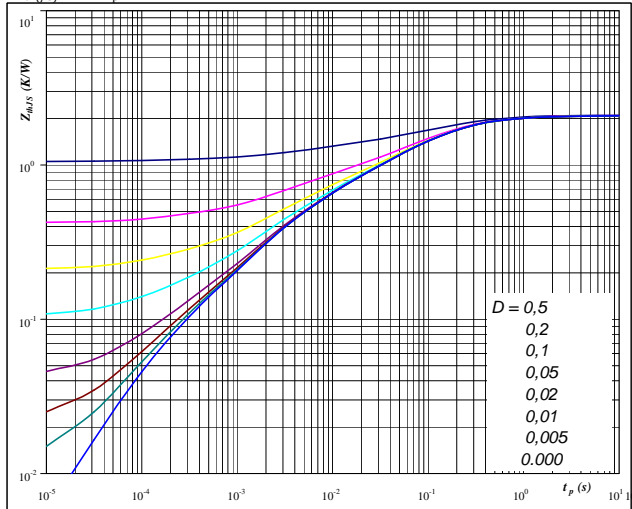


At $D = t_p / T$

$R_{th(f-s)} = 1,19 \text{ K/W}$

figure 12. FWD

FWD transient thermal impedance as a function of pulse width
 $Z_{th(f-s)} = f(t_p)$



At $D = t_p / T$

$R_{th(f-s)} = 2,10 \text{ K/W}$

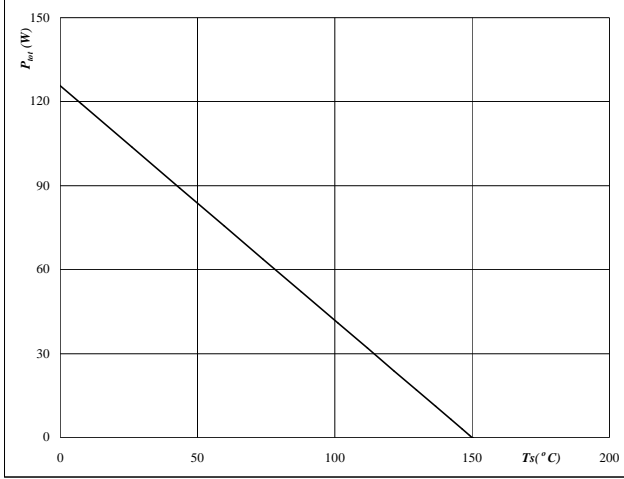


Brake Characteristics

figure 13. IGBT

Power dissipation as a function of heatsink temperature

$$P_{tot} = f(T_s)$$

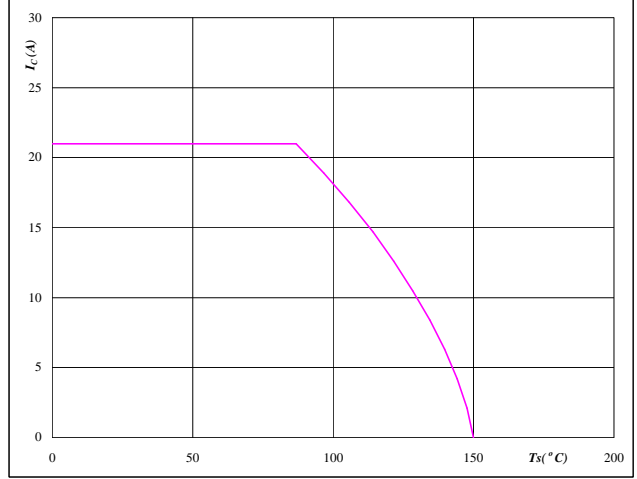


At
T_j = 150 °C

figure 14. IGBT

Collector current as a function of heatsink temperature

$$I_C = f(T_s)$$



At
T_j = 150 °C
V_{GE} = 15 V

figure 15. FWD

Power dissipation as a function of heatsink temperature

$$P_{tot} = f(T_s)$$

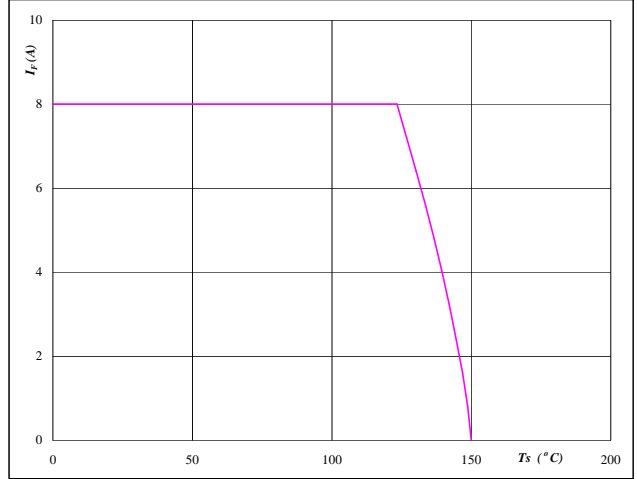


At
T_j = 150 °C

figure 16. FWD

Forward current as a function of heatsink temperature

$$I_F = f(T_s)$$



At
T_j = 150 °C

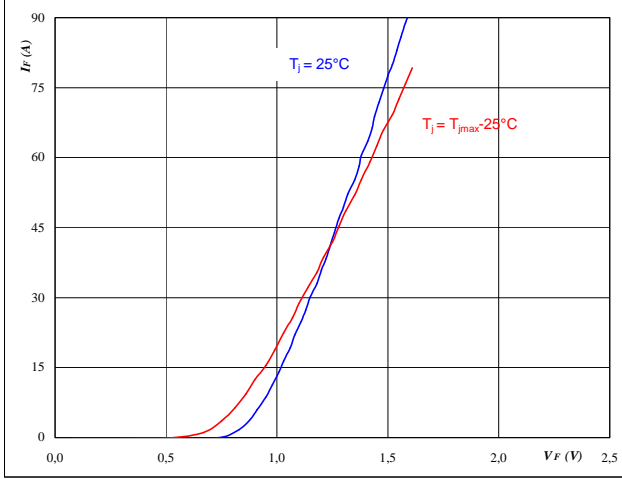


Rectifier Characteristics

figure 1. Rectifier Diode

Typical diode forward current as a function of forward voltage

$$I_F = f(V_F)$$

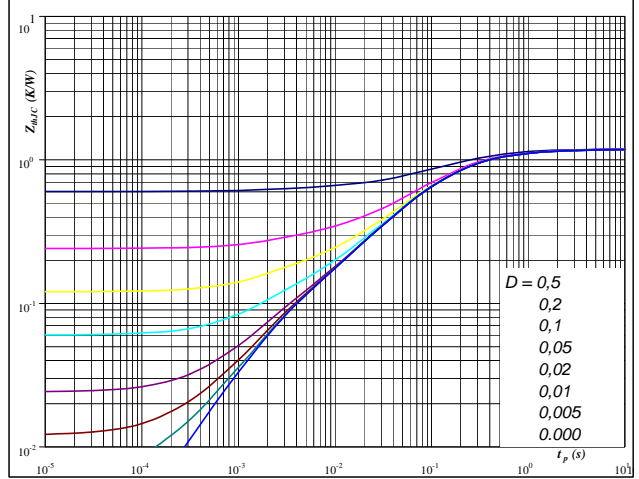


At
 $t_p = 250 \mu\text{s}$

figure 2. Rectifier Diode

Diode transient thermal impedance as a function of pulse width

$$Z_{th(f-s)} = f(t_p)$$

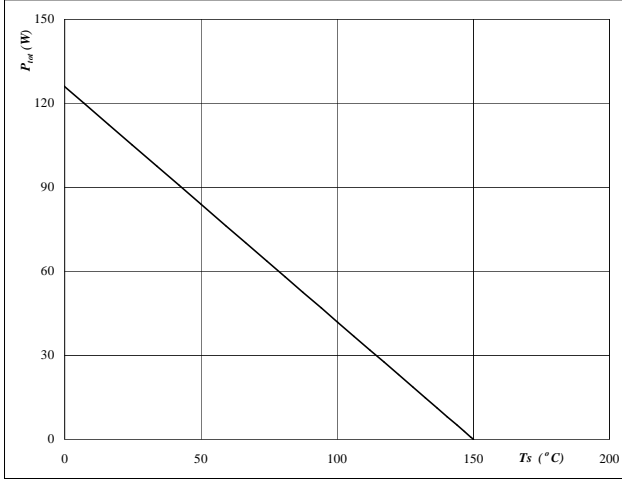


At
 $D = t_p / T$
 $R_{th(f-s)} = 1,19 \text{ K/W}$

figure 3. Rectifier Diode

Power dissipation as a function of heatsink temperature

$$P_{tot} = f(T_s)$$

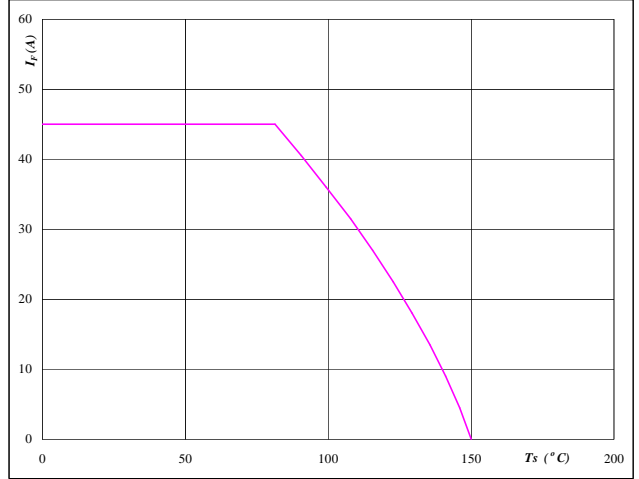


At
 $T_j = 150 \text{ }^\circ\text{C}$

figure 4. Rectifier Diode

Forward current as a function of heatsink temperature

$$I_F = f(T_s)$$



At
 $T_j = 150 \text{ }^\circ\text{C}$

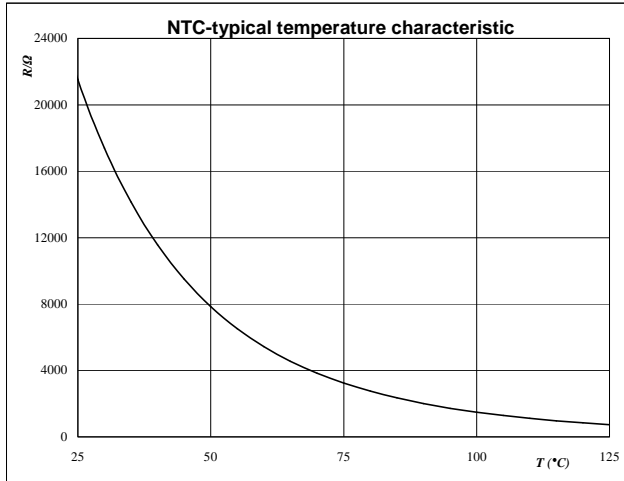


Thermistor

figure 1. Thermistor

**Typical NTC characteristic
as a function of temperature**

$$R_T = f(T)$$



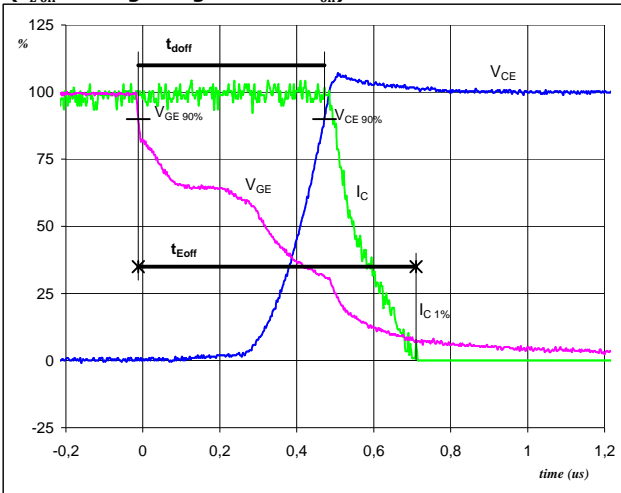


Switching Definitions Output Inverter

General conditions

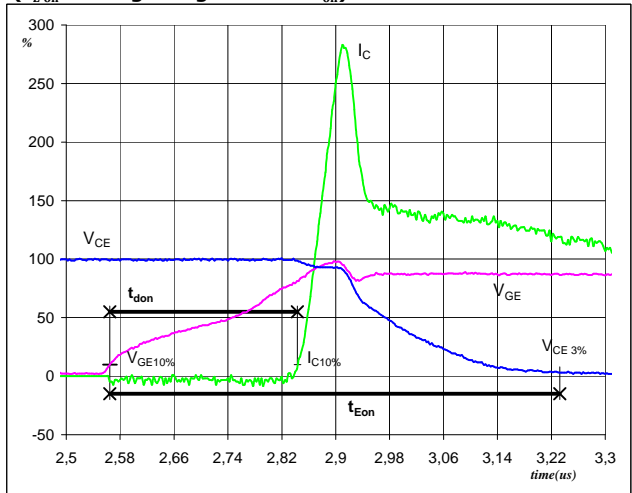
T_j	=	124 °C
R_{gon}	=	36 Ω
R_{goff}	=	36 Ω

figure 1. IGBT
Turn-off Switching Waveforms & definition of t_{doff} t_{Eoff}
(t_{Eoff} = integrating time for E_{off})



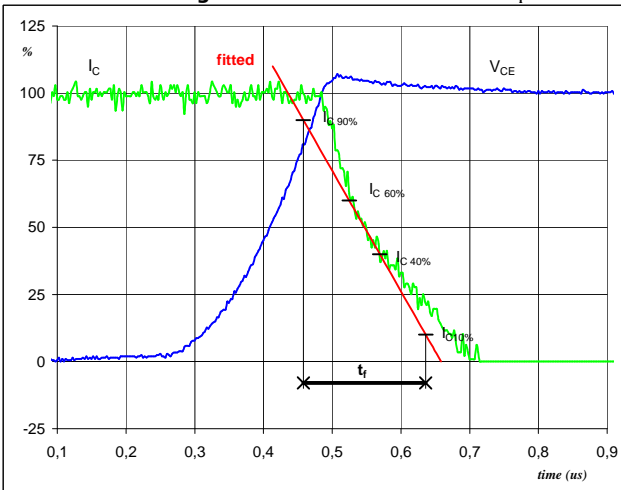
V_{GE} (0%) =	-15	V
V_{GE} (100%) =	15	V
V_C (100%) =	600	V
I_C (100%) =	25	A
t_{doff} =	0,49	μs
t_{Eoff} =	0,72	μs

figure 2. IGBT
Turn-on Switching Waveforms & definition of t_{don} t_{Eon}
(t_{Eon} = integrating time for E_{on})



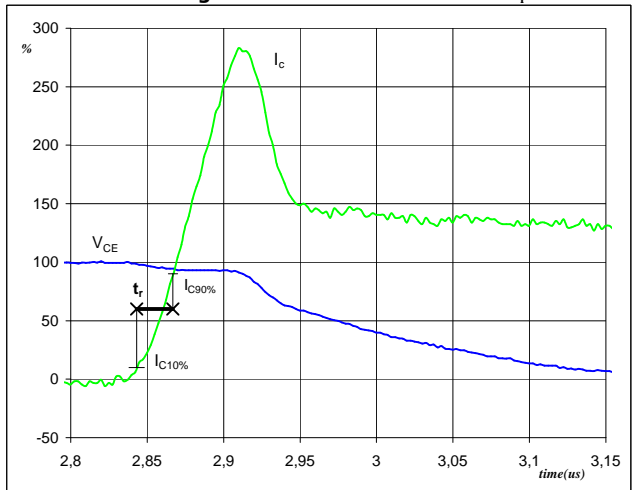
V_{GE} (0%) =	-15	V
V_{GE} (100%) =	15	V
V_C (100%) =	600	V
I_C (100%) =	25	A
t_{don} =	0,27	μs
t_{Eon} =	0,67	μs

figure 3. IGBT
Turn-off Switching Waveforms & definition of t_f



V_C (100%) =	600	V
I_C (100%) =	25	A
t_f =	0,18	μs

figure 4. IGBT
Turn-on Switching Waveforms & definition of t_r

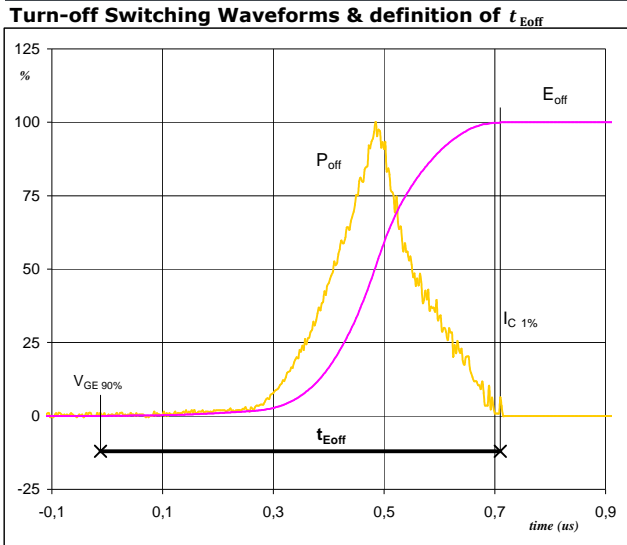


V_C (100%) =	600	V
I_C (100%) =	25	A
t_r =	0,03	μs



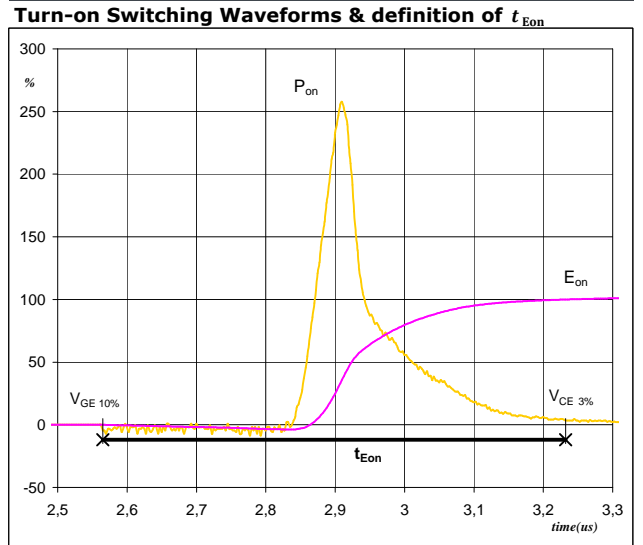
Switching Definitions Output Inverter

figure 5. IGBT



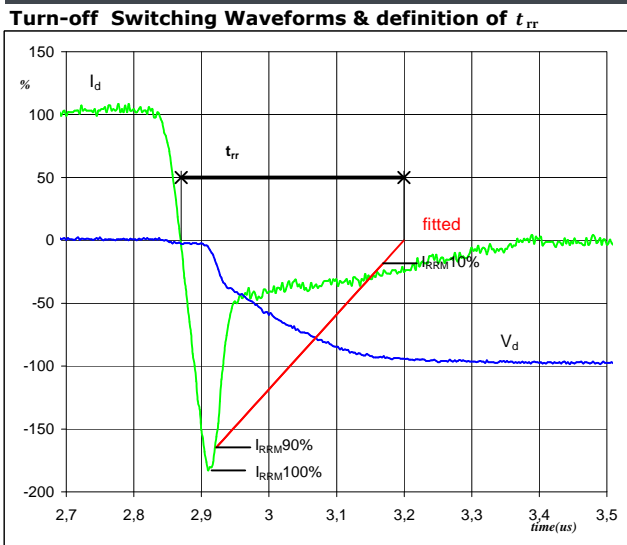
$P_{off} (100\%) = 14,79 \text{ kW}$
 $E_{off} (100\%) = 2,57 \text{ mJ}$
 $t_{Eoff} = 0,72 \text{ } \mu\text{s}$

figure 6. IGBT



$P_{on} (100\%) = 14,79 \text{ kW}$
 $E_{on} (100\%) = 3,45 \text{ mJ}$
 $t_{Eon} = 0,67 \text{ } \mu\text{s}$

figure 7. FWD



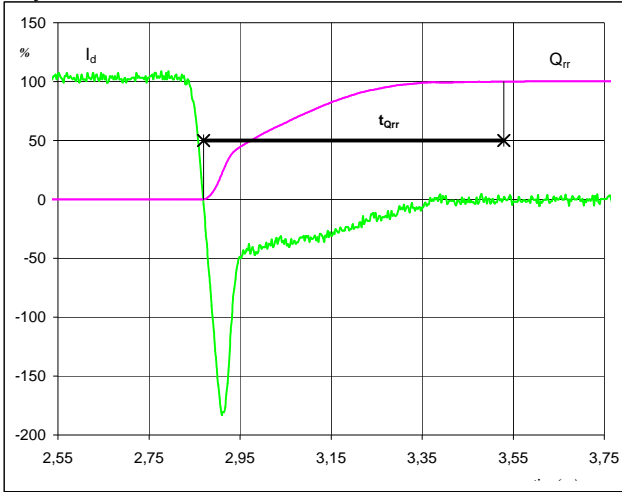
$V_d (100\%) = 600 \text{ V}$
 $I_d (100\%) = 25 \text{ A}$
 $I_{RRM} (100\%) = 46 \text{ A}$
 $t_{rr} = 0,33 \text{ } \mu\text{s}$



Switching Definitions Output Inverter

figure 8. FWD

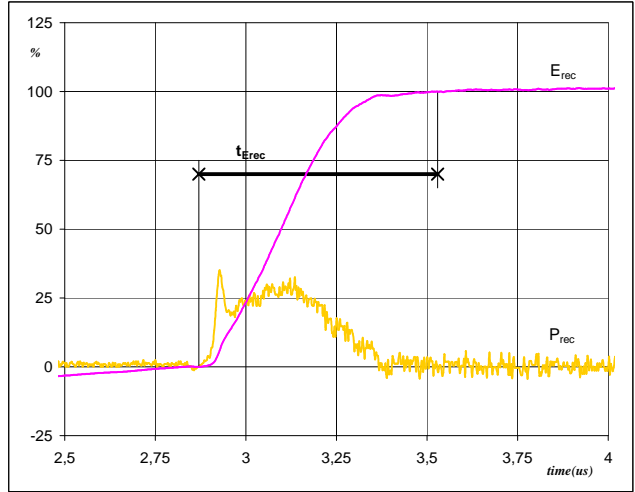
Turn-on Switching Waveforms & definition of t_{Qrr}
(t_{Qrr} = integrating time for Q_{rr})



I_d (100%) =	25	A
Q_{rr} (100%) =	4,82	μC
t_{Qrr} =	0,66	μs

figure 9. FWD

Turn-on Switching Waveforms & definition of t_{Erec}
(t_{Erec} = integrating time for E_{rec})



P_{rec} (100%) =	14,79	kW
E_{rec} (100%) =	1,42	mJ
t_{Erec} =	0,66	μs



Ordering Code and Marking - Outline - Pinout

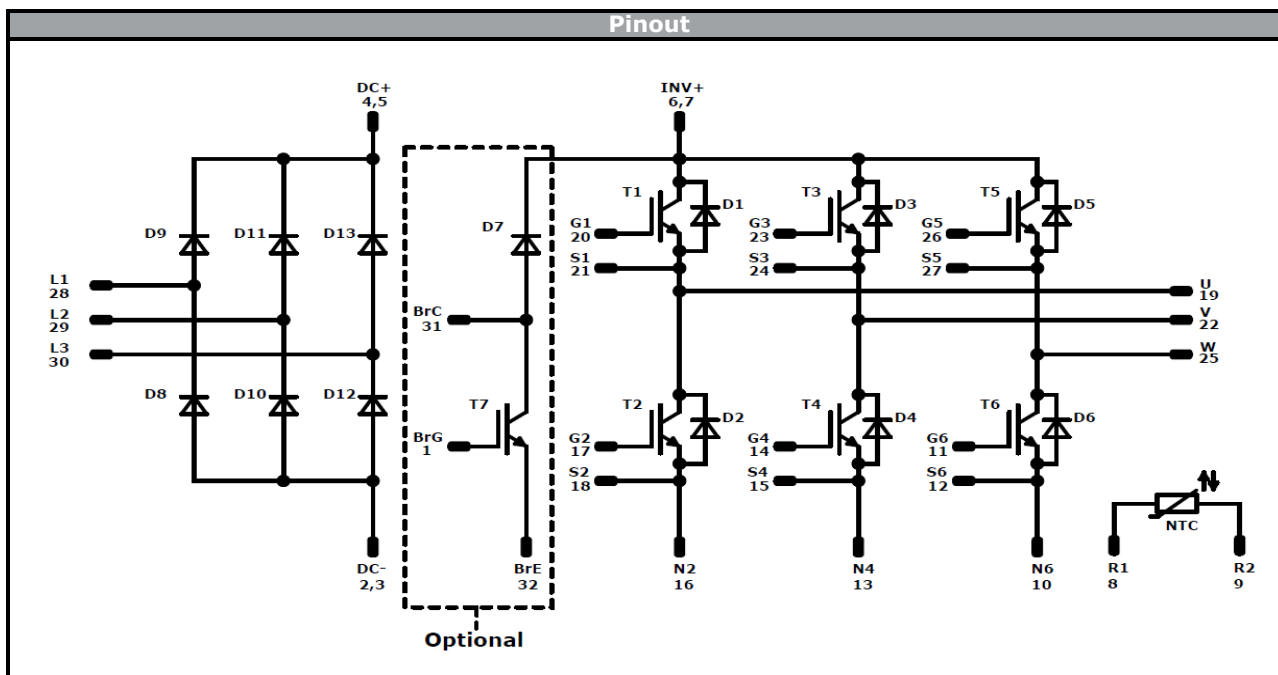
Ordering Code & Marking							
Version			Ordering Code				
without thermal paste 17mm housing with solder pins			V23990-P589-A-PM				
with thermal paste 17mm housing with solder pins			V23990-P589-A-/3/-PM				
without thermal paste 17mm housing with solder pins w/o BRC			V23990-P589-C-PM				
	Text	VIN	Date code	Name&Ver	UL	Lot	Serial
		VIN	WYYY	NNNNNVV	UL	LLLLL	SSSS
Datamatrix	Name&Ver	Lot number	Serial	Date code			
	NNNNNVV	LLLLL	SSSS	WYYY			

Pinout table				Outline	
Pin	X	Y	Function		
1	52,55	0	BrG	<p>Tolerance of pinpositions: ±0.5mm at the end of pins Dimension of coordinate axis is only offset without tolerance</p>	
2	47,7	0	DC-		
3	44,8	0	DC-		
4	37,8	0	DC+		
5	37,8	2,8	DC+		
6	35	0	Inv+		
7	35	2,8	Inv+		
8	28	0	R1		
9	25,2	0	R2		
10	22,4	0	N6		
11	19,6	0	G6		
12	16,8	0	S6		
13	14	0	N4		
14	11,2	0	G4		
15	8,4	0	S4		
16	5,6	0	N2		
17	2,8	0	G2		
18	0	0	S2		
19	0	28,5	U		
20	2,8	28,5	G1		
21	7,5	28,5	S1		
22	14,5	28,5	V		
23	17,3	28,5	G3		
24	22	28,5	S3		
25	29	28,5	W		
26	31,8	28,5	G5		
27	36,5	28,5	S5		
28	43,5	28,5	L1		
29	52,55	25	L2		
30	52,55	16,9	L3		
31	52,55	8,6	BrC		
32	52,55	2,8	BrE		

Pinout variation	
Module subtype	Not assembled pins
V23990-P589-A-PM	-
V23990-P589-C-PM	1, 31, 32



Ordering Code and Marking - Outline - Pinout




Identification					
ID	Component	Voltage	Current	Function	Comment
T1,T2,T3,T4,T5,T6	IGBT	1200 V	25 A	Inverter Switch	
D1,D2,D3,D4,D5,D6	FWD	1200 V	30 A	Inverter Diode	
T7	IGBT	1200 V	15 A	Brake Switch	
D7	FWD	1200 V	6 A	Brake Diode	
D8,D9,D10,D11,D12	Rectifier	1200 V	30 A	Rectifier Diode	
NTC	NTC			Thermistor	



Packaging instruction			
Standard packaging quantity (SPQ)	100	>SPQ	Standard
		<SPQ	Sample

Handling instruction
Handling instructions for <i>flow</i> 1 packages see vincotech.com website.

Package data
Package data for <i>flow</i> 1 packages see vincotech.com website.

UL recognition and file number
This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website. 

Document No.:	Date:	Modification:	Pages
V23990-P589-A-C-D2-14	18 Jul. 2016	New brand, PCM Rth values	all

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.